

05-19-2003



FORM PTO-1595

(Rev. 10/02)

102450644

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U.S. DEPARTMENT OF COMMERCE

Patent and Trademark Office

Docket No.: 67161-012

PATENTS ONLY

To the Honorable Commissioner for Patents and Trademarks: Please record the attached original documents or copy thereto:

1. Name of Conveying Party(ies):  
**Takashi TERADA, Motoi ASHIDA, Tomohiro HOSOKAWA,**  
**and Yasuichi MASUDA**

5-12-03

Additional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

3. Nature of Conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: April 23, 2003

2. Name and address of receiving party(ies):

Name: **RENESAS TECHNOLOGY CORP.,**

Address: 4-1, Marunouchi 2-chome,  
 Chiyoda-ku,  
 Tokyo 100-6334 JAPAN

Additional name(s) & address(es) attached? ☐ Yes ☐ No

4. Application number(s) or patent number(s):

10435046

If the document is being filed together with a new application, the execution date of the application is: April 23, 2003

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached? ☐ Yes ☐ No

5. Name and address of party to whom correspondence  
 concerning document should be mailed:

Name: **MCDERMOTT, WILL & EMERY**

Internal Address:

Street Address: 600 13<sup>th</sup> Street, N.W.

City: Washington State: DC Zip: 20005

6. Total number of applications and patents involved:

7. Total fee (37 CFR 3.41)

\$40.00

☐ Enclosed☒ Authorized to be charged to deposit account

8. Deposit account number:

500417

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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy  
 of the original document.*

Gene Z. Robinson, 33,351

May 12, 2003

Name and Registration No. of Person Signing

Signature

Date

Total number of pages including cover sheet: 1

OMB No. 0651-0027 (exp. 6/30/2005)

05/16/2003 TDI1A21 00000112 500417 10435046

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**PATENT**  
**REEL: 014068 FRAME: 0465**

**ASSIGNMENT**

WHEREAS, Takashi TERADA, Motoi ASHIDA,  
Tomohiro HOSOKAWA, and Yasuichi MASUDA  
hereinafter called the "Assignors," have jointly invented a new and useful invention  
entitled METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE  
, for which he has:

- (a) filed an application for United States Letters Patent on  
 as (Serial No. ); or
- (b) executed an application for United States Letters Patent on  
April 23, 2003; or
- (c) filed a provisional application on   
as (Serial No. ); and

WHEREAS, Renesas Technology Corp., a corporation organized and existing  
under the laws of Japan, having a place of business at:  
4-1, Marunouchi 2-chome, Chiyoda-ku, TOKYO 100-6334 JAPAN, hereinafter  
called the "Assignee," is desirous of acquiring the entire right, title and interest in  
and to said invention, the application above identified, and in, to and under any  
Letters Patent which may be obtained to said invention, as hereinafter more fully  
set forth;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for  
and in consideration of the sum of One Dollar (\$1.00), and other valuable and legally  
sufficient considerations, the receipt of which by said Assignors from the said Assignee  
is hereby acknowledged, the said Assignors have sold, assigned and transferred, and  
by these presents do sell, assign and transfer unto the said Assignee, the entire, right,  
title and interest for the United States in and to the invention and application  
hereinabove identified, and any Letters Patent of the United States that may issue for  
said invention, together with the entire right, title and interest in and to said invention  
and applications for Letters Patent and Letters Patent therefor, in all countries foreign  
to the United States, including the full right to claim for any such application all benefits  
and priority rights under any applicable convention; to have and to hold for the sole and  
exclusive use and benefit of the said Assignee, its successors and assigns, to the full  
end of the term or terms for which any and all of said Letters Patent for said inventions  
may issue.

And the said Assignors do hereby covenant and agree, for himself and his legal representatives, that he will assist the said Assignee in the prosecution of the application herein identified; in the making and prosecution of any other applications for Letters Patent that the said Assignee may elect to make covering the invention herein identified, as hereinabove set forth; in vesting in the said Assignee like exclusive title in and to all such other applications and Letters Patent; and in the prosecution of any interference which may arise involving said invention, or any application or Letters Patent herein contemplated; and that they will execute and deliver to the said Assignee any and all additional papers which may be requested by the said Assignee to fully carry out the terms of this Assignment.

The undersigned hereby grant(s) the attorneys of McDermott, Will & Emery the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

And the Commissioner of Patents and Trademarks is hereby authorized and requested to issue Letters Patent to the said Assignee in accordance with the terms of this Assignment.

IN TESTIMONY WHEREOF, the said Assignors have hereunto set his hands and affixed his seal.

Date: April 23, 2003  
(Seal)

Takashi Terada  
Takashi TERADA

Date: April 23, 2003  
(Seal)

Motoi Ashida  
Motoi ASHIDA

Date: April 23, 2003  
(Seal)

Tomohiro Hosokawa  
Tomohiro HOSOKAWA

Date: April 23, 2003  
(Seal)

Yasuichi Masuda  
Yasuichi MASUDA